IPC ASSOCIATION ELECTRONIC	© Copyright 2005.	Material Composition Declaration © Copyright 2005. IPC, Bannockburn, Illinois. All rights reserve international and Pan-American copyright conventions.			der both	This document is a declaration of the substances within the manufacturer listed item. Note: if the item is an assembly with low level parts, the declaration encompasses all lower level materials for which the manufacturer has engineering responsibility.									
1752-21.1	IPC Web Site for Information on IPC-1752 Standard Form Typhttp://www.ipc.org/IPC-175x Distribute				Declaration Class * Class 6 - RoHS Yes/No, Homogeneous Materi					rials and M	ials and Mfg Information				
Supplier	Information														
Company name* Company un				rique ID			Unique ID Authority					Response Date*			
onsemi											2025-00	2025-06-07			
Contact N	ame		Title - Contact			1	Phone - Contact*				Email -	Email - Contact*			
Product-I	Env-Stewards		Product Enviro Compliance				NA				Product-Env-Stewards@onsemi.com				
uthorize	d Representative*	Title - Representative			I	Phone - Representative*				Email -	Email - Representative*				
Product-H	Env-Stewards	Product Enviro Compliance				NA				Produ	Product-Env-Stewards@onsemi.com				
	Requester Item Number Mfr Iter		n Number Mfr Item Name				Effective Da	ve Date Version Manufacturing Site		Manufacturing Site		Weight*	UOM	Unit Type	
		CAT5241YI-10-T2 DPP NV, QUAD		DPP NV, QUAD 6	4 TAPS, I2C		2025-06-07 TH6		ТН6		78.25	mg	Each		
Manufa	cturing Process Informa	ation						·						·	
	Terminal Plating / Grid Array Material Terminal Base A			e Alloy J-STD-020 MSL Rating			Peak Process Body Temperature Max Time at Peak				Temperature Number of Reflow Cycles				
Matte Tin (Sn) - annealed CU Alloy 1						260		C	30	seco	nds 3				
Comments															
evel 1 - m	aximum time at peak tempera	ture during sol	dering is 10-3	30 seconds											
or more i	information regarding materia	l composition	please refer to	page 3											

RoHS Material Composition Declaration			Declaration Type *	Detail	ed				
Directive 2015/863/EU amending RoHS Directive 2011/65/EU		ium (Cr6+), Polybrominated Biphenyls (PB)	erial for Cadmium and quantity limit of 0.1% b B), Polybrominated Diphenyl Ethers (PBDE), a						
cadmium, hexavalentchromium, polybromin contains a RoHS restricted substance inexce encompass all such components. Supplier cet as of the date that Supplier completes this Company acknowledges that Supplier may hindependently verified information provided certification in this paragraph. If the Compan	nated biphenyls and/or polybrominated diphess of an applicable quantity limit, please indriffes that it gathered the information it provom. Supplier acknowledges that Company wave relied on informationprovided by others of the supplier agrees that, at a minimusy and the Supplier enter into a written agree yesource of the Supplier's liability and the C	enyl ethers (each a "RoHS restricted substan licate below which, if any, RoHS exemption vides in this form using appropriate methods vill rely on this certification in determining the s in completing this form, and that Supplier um, itssuppliers have provided certifications ement with respect to the identified part, the tompany's remedies for issues that arise rega	s of the European Union member states) of the ce") in excess of the applicable quantity limit is you believe may apply. If the part is an assemb to ensure its accuracy and that such informatio e compliance of its products with European Ur may not have independently verified such infor regarding their contributions to the part, and the erms and conditions of that agreement, including information the Supplier provides in this	dentified above. If a ally with lower level in is true and correct tion member state la mation. However, in ose certifications are ag any warranty righ	homogeneous material within the part components, the declaration shall to the best of its knowledge and belief, was that implement the RoHS Directive. In situations where Supplier has not the at least as comprehensive as the lats and/or remedies provided as part of				
RoHS Declaration * 1 - Item	(s) does not contain RoHS restricted substar	nces per the definition above	Supplier A	cceptance *	Accepted				
Exemption: If the declared item does not contain RoHS restricted substances per the definition above except for defined RoHS exemptions, then select the corresponding response in the RoHS Declaration above and choose all applicable exemptions.									
Exemption List Version	EL-2011/534/EU								
Declaration Signature									
		e "Accepted" on the Supplier Acceptance	drop-down. This will display the signature a	rea. Digitally sign t	the declaration (if required by the				

Homogeneous Material Composition Declaration for Electronic Products

SubItem Instructions: The presence of any JIG Level A or B substances must be declared. [1] indicate the subpart in which the substance is located, [2] provide a description of the homogeneous material [3], enter the weight of the homogeneous material.

Substance Instructions: [A] select the Level (JIG A, JIG B, Requester or Supplier) [B] select the substance category (JIG or Requester) or enter a value (Supplier). [C] select the substance (JIG) or enter the substance and CAS (Other). [D] select a RoHS exemption, if applicable [E] enter the weight of the substance or the PPM concentration [F] Optionally enter the positive (+) and negative (-) tolerance in percent (Note: percent tolerance values are expected to cover a 3 sigma range of distribution unless otherwise noted).

Homogeneous Material	Weight	Unit of Measure	Level	Substance	CAS	Exempt	Weight	Unit of Measure
Die	4.62	mg	Supplier	Silicon (Si)	7440-21-3		4.62	mg
Die Attach	0.57	mg	Supplier	Silver (Ag)	7440-22-4		0.4275	mg
			Supplier	Epoxy resins	129915-35-1		0.1425	mg
Lead Frame	23.33	mg	Supplier	Silver (Ag)	7440-22-4		0.7839	mg
			Supplier	Magnesium (Mg)	7439-95-4		0.035	mg
			Supplier	Silicon (Si)	7440-21-3		0.1516	mg
			В	Nickel (Ni)	7440-02-0		0.6999	mg
			Supplier	Copper (Cu)	7440-50-8		21.6596	mg
Mold Compound-Black	46.99	mg		Epoxy Phenol Resin	proprietary data		4.9339	mg
			Supplier	Fused Silica (SiO2)	60676-86-0		42.056	mg
Plating	2.15	mg	Supplier	Tin (Sn)	7440-31-5		2.15	mg
Wire Bond - Au	0.59	mg	Supplier	Gold (Au)	7440-57-5		0.59	mg